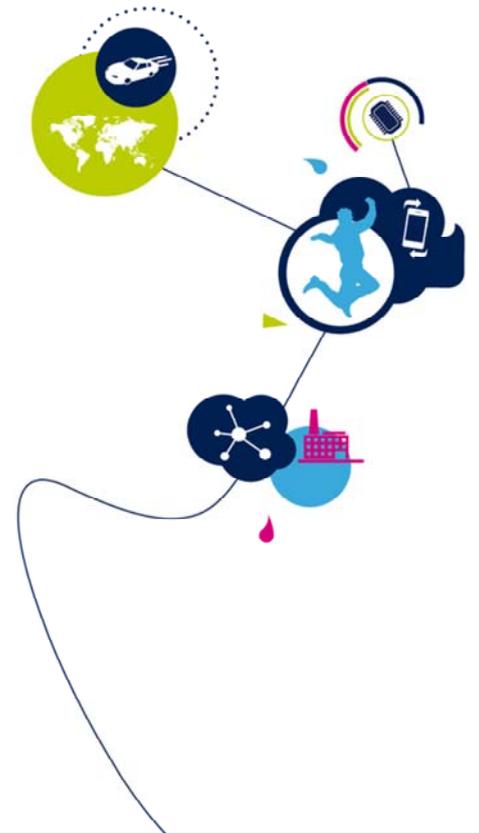


STM32MP1 – SERIES

Series presentation
Revision 2.0



Hello, and welcome to this introduction to the STM32MP1 series.
This short presentation describes the various lines available in the STM32MP1 series of high-performance MPUs with an Arm Cortex-A7 core.

STM32MP1 Series product line

ACCELERATION • Dual core* Arm Cortex A7 processor • L1 and L2 caches • 3D Graphic Processing Unit* • Floating Point Unit + Arm NEON* • Arm Cortex M4 209MHz coprocessor • MDMA + DMA • LPDDR2/LPDDR3 6/32**-bits @3MHz • DDR3/DDR3L 6/32**-bits @3MHz	Product line	f _{CPU} (MHz)	Cortex A7 cores	f _{MCU} (MHz)	Cortex M4 cores	f _{CPU} (MHz)	Cortex A7 L1 cache (D)	Cortex A7 L2 cache	RAM (Kbytes) + 6K retention + 4K backup	HW Crypto	3D GPU	FDCAN
CONNECTIVITY • 2 x USB2.0 HS Host • USB2.0 OTG FS/HS • 3 x SDMMC/SPIO • UART, UART, SPI, I2C • 2 x ITT/FDCAN2.0* • HDMI-CEC • Ggabit Ethernet EEE 688*** • MIC (NAND Flash) • Camera IF • Dual mode Quad-SPI • DSI 25bits* AUDIO • 1 S+audio PLL • 4 x SAI + 8 x I2S/M + SPDIF-RX • 2 x 12-bit DAC OTHER • 6- and 32-bit timers • 2 x 10-bit ADC (7.2 Mbps)	STM32MP151A	800	1	-	1	-	32K+32K + 256K		•	-	-	-
	STM32MP151D	800	1	-	1	-	32K+32K + 256K		•	-	-	-
	STM32MP151F	800	1	-	1	-	32K+32K + 256K		•	-	-	-
	STM32MP153A	800	2	209	1	-	2x 62K+32K + 256K		•	-	-	2
	STM32MP153C	800	2	209	1	-	2x 62K+32K + 256K		•	-	-	2
	STM32MP153D	800	2	209	1	-	2x 62K+32K + 256K		•	-	-	2
	STM32MP153F	800	2	209	1	-	2x 62K+32K + 256K		•	-	-	2
	STM32MP157A	800	2	209	1	93	2x 62K+32K + 256K		•	•	-	2
	STM32MP157C	800	2	209	1	93	2x 62K+32K + 256K		•	•	-	2
	STM32MP157D	800	2	209	1	93	2x 62K+32K + 256K		•	•	-	2
	STM32MP157F	800	2	209	1	93	2x 62K+32K + 256K		•	•	-	2



Notes:

* not available in all product lines

** 16/32-bits for LFBGA448 and TFBGA351 packages, 16-bits only for LFBGA354 and TFBGA257 packages

*** 10/100M Ethernet only for LFBGA354 and TFBGA257 packages

Taking advantage of L1 and L2 caches, STM32MP15x microprocessors deliver the maximum theoretical performance of the Cortex-A7 core no matter whether the code is executed from the embedded RAM or an external memory: up to 2568 CoreMark at 800 MHz f_{CPU} for each core.

- The STM32MP151 line offers the performance of a single Cortex-A7 core (with floating point unit and NEON SIMD Engine) running up to 800 MHz, plus a Cortex-M4 with FPU which offer up to 703 Coremark at 209 MHz f_{MCU} for real time peripheral processing. The STM32MP151C integrates a crypto processor providing hardware acceleration for AES-128, -192 and -256, with support for GCM and CCM, Triple DES functions.
- The STM32MP153 line expands the family to double Cortex-A7 core, doubling the available Coremark to 5136 at 800 MHz f_{CPU} , plus additional interfaces such as two FDCAN, one having TT option. The STM32MP153C

integrates a crypto processor.

- The STM32MP157 line offers in addition a 3D GPU for complex image composition (up to 26M triangles/sec or 133M pixels/sec at 533MHz f_{GPU}) and a MIPI-DSI interface (up to 1366x768 at 60fps). The STM32MP157C integrates a crypto processor.

STM32MP157F block diagram

• Available packages

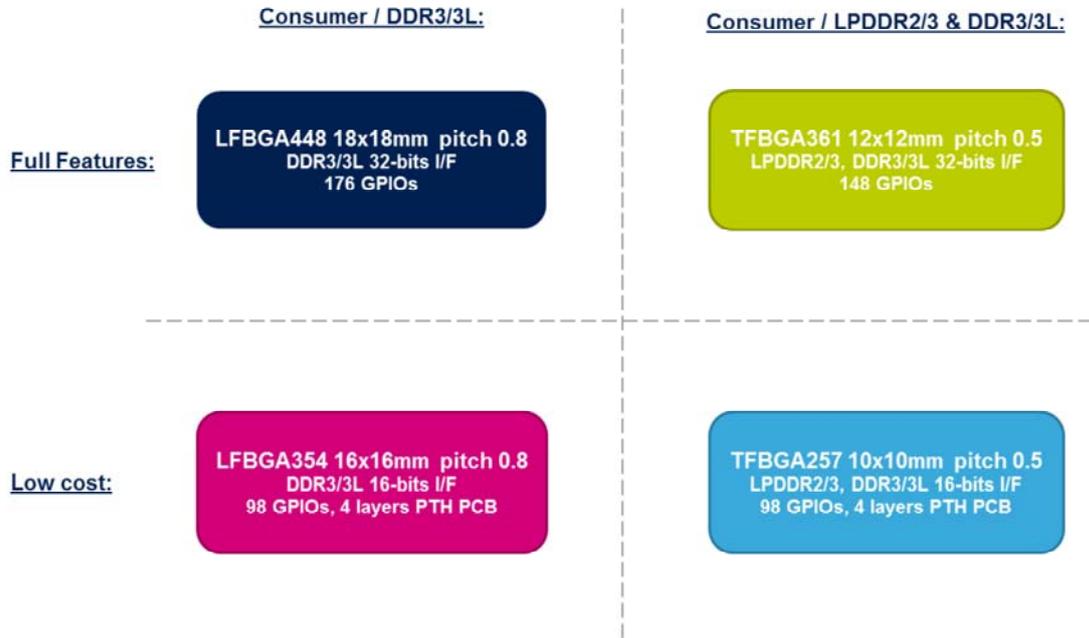
- LFBGA448 18x18 pitch 0.8
- LFBGA354 15x15 pitch 0.8
- TFBGA361 12x12 pitch 0.5
- TFBGA257 10x10 pitch 0.5



Not Available on all product lines



This block diagram summarizes the key features and the available packages for STM32MP157F devices. The STM32MP157F line integrates the dual Cortex-A7 core (with floating point unit and NEON SIMD Engine) running up to 800MHz, with 708 Kbytes of SRAM in total and up to 35 communication interfaces in addition to a 3D Graphic Processing Unit and an LCD-TFT controller with a parallel or DSI interface for advanced graphics processing. Boxed red blocks are not available on all product lines.



The four packages are optimized for a wide range of usage. Full feature packages provide maximum available GPIO count, and exist in pitch 0.8mm for robust and low-cost PCB as well as pitch 0.5mm for smaller PCB footprint. Low cost packages are optimized for low cost Plated-Through Hole (PTH) PCB routing and are available in two different ball pitch for low-cost PCB or small PCB footprint.